

Ref #	Hits	Search Query	DBs	Default Operator	Plurals	Time Stamp
L2	150	(molding potting) adj3 resin with (fiber fibrous)and (chip die ic) same (substrate board carrier interposer)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/05 14:14
L4	6366	resin with (fiber fibrous) and (chip die ic) same (substrate board carrier interposer)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/05 14:14
L5	29541	encapsulant adh (resin epoxy) with (fiber fibrous) and (chip die ic) same (substrate board carrier interposer)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/05 14:15
L6	4	encapsulant adj2 (resin epoxy) with (fiber fibrous) and (chip die ic) same (substrate board carrier interposer)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/05 14:18
L7	227	mold\$4 adj2 (resin epoxy) with (fiber fibrous) and (chip die ic) same (substrate board carrier interposer)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/05 15:06
L9	146	(mold\$4 encapsulat\$4) with (resin epoxy) with (fiber fibrous) with carbon and (chip die ic) same (substrate board carrier interposer)	US-PGPUB; USPAT; EPO; JPO; DERWENT; IBM_TDB	OR	ON	2006/02/05 15:07